REDUCED FOOTPRINT PACKAGED MICROELECTRONIC COMPONENTS AND METHODS FOR MANUFACTURING SUCH MICROELECTRONIC COMPONENTS

ABSTRACT OF THE DISCLOSURE

The present disclosure describes microfeature workpieces, microelectronic component packages, and methods of forming microelectronic components and microelectronic component packages. In one particular example, a microelectronic component package includes a substrate and a microelectronic component that has a first surface with a surface area greater than that of a second surface. A cementitious material, e.g., a die attach paste, may attach the second surface of the microelectronic component to a mounting surface of the substrate, with the cementitious material extending outwardly beyond a perimeter of the second surface and covering a surface area of the mounting surface that is no greater than the surface area of the first surface. Such a microelectronic component package may be formed with a smaller footprint or, alternatively, may include a microelectronic component having larger dimensions in a microelectronic component package of the same size.

Figure 3